c) Amendment to the Claims

Please cancel claims 1, 2 and 9 and amend claims 4-8 and 11-13 as follows. A detailed listing of all the claims that are or were in the application is hereafter provided.

Claims 1 and 2 (Cancelled)

3. (Original) A method of manufacturing an electroconductive film, comprising the steps of:

sequentially repeating a film forming step of forming a film containing a photosensitive material and an electroconductive material therein and an exposure step of irradiating a light onto a desired region of said film formed in said film forming step for a plurality of times to laminate said films on each other into a laminate film where the latent images of the respective layers are integrated into a laminate latent image;

developing the latent image into a development image by removing a non-latent image region of said laminate film after the formation of said laminate film together; and

baking said development image formed in said developing step.

4. (Original) A method according to claim 3, wherein the latent images of the laminated second and subsequent layers are formed with a size different from that of the first layer on the substrate in said laminate film forming step.

5. (Currently Amended) A method according to claim ~~2 or~~ 4, wherein an opening region of an opening portion of a mask having said opening portion for irradiating a light onto a desired region of said film is changed to form said latent image with a different size in said exposure step.

6. (Currently Amended) A method according to claim ~~2 or~~ 4, wherein a distance between a mask having an opening portion for irradiating a light onto a desired region of said film and said film is changed to form said latent image with a different size in said exposure step.

7. (Currently Amended) A method according to any one of claims 3-6 ~~claims 1 to 6~~, wherein a film thickness after said baking step is 5 μm or more.

8. (Currently Amended) A method of manufacturing image forming apparatus comprising the steps of:

forming a first and second wirings in a matrix according to the electroconductive film manufacturing method recited in any one of claims ~~1 to 7~~ 3-7 so that an insulating layer is interposed between the first and second wirings at an ~~interection~~ intersection of the first and second wiring;

forming an electron emission element at the intersection of the first and second wirings; and

providing an image forming member which forms an image by using electrons emitted from the electron emission element.

9. (Cancelled)

10. (Original) A method of manufacturing an electroconductive film, comprising the steps of:

sequentially repeating a film forming step of forming a film containing a photosensitive material and an electroconductive material therein on a substrate and an exposure step of irradiating a light onto a desired region of said film containing the photosensitive material and said electroconductive material which has been formed in said film forming step for a plurality of times to form a laminate film into which a plurality of films each having an exposed region and a non-exposed region are laminated;

removing the non-exposed region of said laminated film where the photoconductive material is a negative type or the exposed region of said laminated film where the photoconductive material is a positive type; and

baking said laminate film that has been subjected to said developing step.

11. (Currently Amended) A method according to claim ~~9 or~~ 10, wherein said film forming step coats a paste containing said photosensitive material and said electroconductive material therein on said substrate.

12. (Currently Amended) A method according to claim ~~9 or~~ 10, wherein said electroconductive material is metal.

13. (Currently Amended) A method according to claim ~~9 or~~ 10, wherein said electroconductive material is electroconductive grains.